INTEGRA
TECHNOLOGIES

Trusted Source for Engineering & Test Services

The Defense Microelectronics Activity (DMEA) has accredited Integra Technologies as a DOD Category 1A Trusted Supplier for Die Prep, Assembly, Qualification, Test and Broker Services.

As a Trusted supplier, Integra offers full turnkey semiconductor die prep, assembly, test software development, testing, qualification, characterization and other related technical services. Integra's significant investment in back end wafer processing has enabled us with the largest capacity in North America for wafer thinning, dicing, inspection, and die-sort. Integra can assemble a wide variety of JEDEC and custom IC packages, including open-cavity (hermetic & non-hermetic), QFN/DFN, BGA/LGA, uBGA, CSP, Imaging devices, COB, & system in package solutions (SIP). Integra's electrical test services encompass both final test and probe. Integra has one of the largest and most experienced test engineering organizations in the industry. Integra has earned an outstanding reputation for quality, consistency, and on-time delivery.

Die Prep Service Portfolio

- Standard processing thinning accuracy +/- 0.5mil from target and thickness down to 50µm
- Total thickness variation < 6µm
- Individual die through 300 MM wafers
- Variety of materials such as Si, AlN, GaN, GaAs, InP, SiC, and Sapphire

Complete Assembly Solution

- Die attach (epoxy, die attach film, silver glass, eutectic)
- Flip Chip
- Wire bonding Al and Au wires (0.5mil - 2.0 mil)
- BGA
- QFN
- CSP
- SIP
- Mark & pack (ink, laser, serialization, tape & reel, FGI, drop ship)

Complete Test Solution

- Design & FAB Load Boards
- Design & FAB Probe Cards
- Design & FAB Burn-in Boards
- Design & FAB HAST Boards
- Design & FAB ESD Test Fixtures
- Develop & Execute Characterization Plan
- Develop & Execute Qualification Plan
- Pre-Production Wafer Probe
- Pre-Production Package Test
- Production Wafer Probe
- Production Package Test
- MPS Management Systems
- Inventory Management

Test Platforms

High End Mixed Signal & Digital

- Verigy 93000
- Teradyne J750
- Teradyne Catalyst RF
- Teradyne IP750 (in clean environment)

CMOS Imager Sensor

- Teradyne IP750 (in clean environment)

Digital Testers

- Verigy 93000
- Teradyne J750
- Teradyne Catalyst RF
- Teradyne IP750
- Nextest Maverick II (GT & PT)
- Chroma 3650

Linear & Mixed Signal

- Credence ASL1000
- Credence ASL3000
- Focused Test FTI-1000

Memory Testing

- Verigy 93000
- Nextest Maverick II (GT & PT)

RF Testing

- ASL3000 RF
- Custom Set-up: 50+ GHz
- Keysite N5225 PNA
- Teradyne Catalyst RF

Process Screening

- Turnkey Manufacturing Solution
- Electrical Test
- Wafer Probe, up to 300mm -40°C to +150°C
- Up-screening to Mil temps
- Counterfeit Verification
- Qualification
- Military & Aerospace Processing
  - MiL-PRF 38535
  - MiL-PRF 19500
  - MiL-STD 883
  - MiL-STD 750
  - MiL-STD 202
  - EEE INST-001
  - EEE INST-002
  - JEDEC
  - ANSI

Celebrating Over 35 Years of Providing
High Quality Semiconductor Services

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